

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

DFN 3mm X 2mm Exp. Pad

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**TOTAL MASS (g) : 0.013426**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000727	1000000	54150.2539062		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004211	974800.0625	313654.375		
		Iron (Fe)	7439-89-6	0.000102	23500	7597.42236328		
		Phosphorus (P)	7723-14-0	0.000004	850	297.938110352		
		Zinc (Zn)	7440-66-6	0.000004	850	297.938110352		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.004321</b>	<b>1000000</b>	<b>321847.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000185	1000000	13750.3291016		
		<b>External Plating Total:</b>				<b>0.000185</b>	<b>1000000</b>	<b>13750.3291016</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000103	1000000	7671.90673828		
<b>Internal Plating Total:</b>				<b>0.000103</b>	<b>1000000</b>	<b>7671.90673828</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000005	50000	372.422668457		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000032	300000	2383.50488281		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000070	650000	5213.91699219		
<b>Die Attach Total:</b>				<b>0.000107</b>	<b>1000000</b>	<b>7969.84521484</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001034	130000	77017		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.006837	860000	509250.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000080	10000	5958.76269531		
		<b>Encapsulation Total:</b>				<b>0.007951</b>	<b>1000000</b>	<b>592226.5</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000032	1000000	2383.50488281		
					<b>TOTAL MASS (g) :</b>	<b>0.013426</b>		